

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:
Rajeev Joshi et al.

Serial No.: 10/731,453

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For: WAFER-LEVEL CHIP SCALE PACKAGE AND
METHOD FOR FABRICATING AND USING THE
SAME

Confirmation No. 4432

Group Art Unit: 2891

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Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION
UNDER 37 C.F.R. § 1.114

Applicant hereby files the accompanying Request for Continued Examination and, therefore, requests reconsideration of this application in light of the following amendments and remarks.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.